

SID

Factory: Rot am See

Article:

475

ML4

Provided:

Kracht, Enrico

Customer:

Date:

08.06.2015



Processtechnology: B: undefiniert

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1	A00 B00
A-RS-FR4-Prepreg-7628-TG150-HF	50200643	363		2	
A-RS-FR4-Prepreg-7628-TG150-HF	50200643	0		3	
B-RS-FR4-DS-1.55mm-035+035-TG150-HF	50200664	35	L2		
		1480		4	
		35	L3		
A-RS-FR4-Prepreg-7628-TG150-HF	50200643	363		5	
A-RS-FR4-Prepreg-7628-TG150-HF	50200643	0		6	
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	7	

Thickness after Pressing

B00:

2290 µm

Tol+:

240 µm

Tol-:

240 µm

Dmax:

2530 µm

Dmin:

2050 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

2400 µm

Tol+:

240 µm

Tol-:

240 µm

Dmax:

2640 µm

Dmin:

2160 µm

Measuring point: (05) über LM und galv.Cu; beidseitig

nominal:

2312 µm

Version 1.2.14.15

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